

regions corresponding to the removed socket 23a shown by the dotted line. Alternatively, the connector pins 25 can be formed on the rear surface on regions corresponding to all sockets 23 without removing any of the sockets.

5 A connector 27 is preferably attached and electrically connected to the connector pins 25. The connector 27 is connected to an interface board 29 using contact or soldering methods. In this embodiment, the connector 27 is connected to the interface board 28 using connector pins (not shown) which are the same as the connector pins 25. Test sockets 31 for semiconductor devices are mounted on the interface board 29 for coupling the semiconductor devices to the circuit board 21 through the connector pins 25.

10 Since the connector pins 25 protrude from the rear surface of the mother board 21, the arrangement of the connector pins 25 is in the reverse order from the front surface of the mother board 21. The interface board 29 can be designed to again reverse this reverse arrangement of the connector pins 25, thereby allowing the use of a standard socket to couple a semiconductor device to the interface board.

15 The interface board 29 can be used simply to reverse the arrangement of the connector pins, or it can be designed to serve other functions as well. For example, it can be used to create a test environment for the semiconductor devices (in this example, memory devices) within the sockets 31 which are actual operating conditions that the devices might encounter on the circuit board. That is, the interface board 29 can be designed to compensate for the environmental differences caused by use of the sockets 31, as well as the use of additional equipment that might be added. An example of such an interface board is disclosed in Korean Patent Application No. 2000-20653 entitled "Interface Board And Test Method For Semiconductor Integrated Circuit Devices Using The Same." which is incorporated by reference, and U.S. Patent Application Ser. No. 09/733,336, filed December 8, 2000,
20 entitled, *now Pub. No. 2001/6034865*,
25 "Method And Apparatus For Testing Semiconductor Devices Using An Actual Board-Type Product" which is incorporated by reference. For example, this compensation can include the control of the clock signal timing, the control of the signal timing margin, the control of AC signal parameters, and the control of the power supply signals.

The interface board 29 is supported between the interface board 29 and the mother board 21 by supports 33, and fixed to the mother board 21 by fasteners 35, thereby attaching the interface board firmly to the mother board.

To test a semiconductor device using the system 20 of Figs. 5-7, the device is inserted into a socket 31, the interface board 29 is attached to the back side of the mother board 21 through connector pins 25, and the circuitry on circuit board 21 is then operated. In the case